

Allied High Tech Products, Inc.

2020 Product/Application Overview

Introduction

Allied High Tech Products, Inc.

- 35+ years
- Specializing in Sample Preparation

Gary Liechty – gdliechty@alliedhightech.com

- 25+ years experience in sample prep
- Author/co-author and contributor to several (IEEE) published works on sample prep
- Co-inventor/engineer of the MultiPrep (1998)
 - Over 3K units worldwide
- Co-developer X-Prep (2008)
 - 150+ units worldwide

MultiPrep

- X** High precision grinding/polishing machine
- X** Precision mechanical control of sample
 - Tilt/axis control
 - Dynamic and static indication of position/material removal
- X** Suited mostly for small/unencapsulated samples - contemporary applications
 - Flat wheel/platen uses disc form abrasives/cloths for grinding/polishing
- X** Introduced 1998
 - Optical and Electron Microscopy Sample Prep
 - Semiconductor, Material Research
- X** Cross-sectioning for SEM/TEM sample prep
 - Package – Defect Analysis
 - Solder ball/bond wire and die attach
 - Au (2005) – Cu (2004 to present) – Ag & SnPb to SnAg (RoHs) – artifacts in prep
 - Thin-film (TEM)
- X** Parallel delayering/deprocessing
 - Die level deprocessing/reverse engineering
 - Challenges with uniformity due to curvature

X-Prep

- X** Highly specific, precision mechanical (CNC type) milling instrument introduced 2008
 - Small diameter cutting and diamond grinding tools as well as polishing abrasives
 - Non-planar sample prep
- X** Semiconductor applications (mostly)
- X** Addresses challenges of semi in shrinking scale/package density and complexity due to drive to newer technologies
 - Curvature, stress/warpage
 - Enables EFI for DPA – locate (electrical) the physical defect, verify through cross-section (physical dest.)
- X** Extends benefits of CNC milling to FA with easier to use interface and level of precision required in semi
- X** Uses miniature cutting and diamond grinding tools for mechanical removal (cutting/grinding) of materials without damage to the functionality of the sample/device
 - Highly versatile
 - Micron level precision

Thank you for your attention.

 Questions?